

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 15 A
V_{RRM}	40 V
T_j (max)	150 °C
V_F (max)	0.50 V

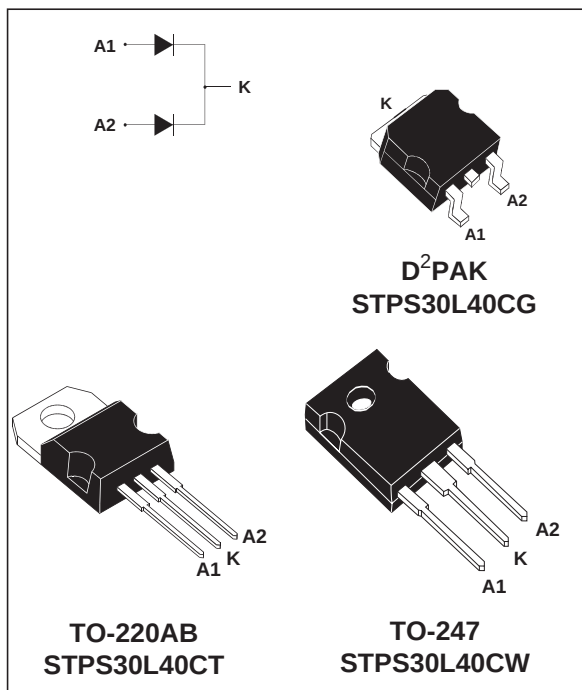
FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Dual center tap schottky rectifiers suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in TO-247, TO-220AB and D²PAK these devices are intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			40	V
I _{F(RMS)}	RMS forward current			30	A
I _{F(AV)}	Average forward current	T _c = 135°C δ = 0.5	Per diode Per device	15 30	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal		220	A
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs square F=1kHz		1	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100 μs square		3	A
P _{ARM}	Repetitive peak avalanche power	t _p = 1μs T _j = 25°C		6000	W
T _{stg}	Storage temperature range			- 65 to + 150	°C
T _j	Maximum operating junction temperature *			150	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

STPS30L40CG/CT/CW

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode Total	1.60 0.85	°C/W
$R_{th(c)}$		Coupling	0.10	°C/W

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I_R^*	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			360	μA
		$T_j = 100^\circ\text{C}$			20	50	mA
V_F^*	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 15\text{ A}$			0.55	V
		$T_j = 125^\circ\text{C}$	$I_F = 15\text{ A}$		0.42	0.50	
		$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$			0.74	
		$T_j = 125^\circ\text{C}$	$I_F = 30\text{ A}$		0.59	0.67	

Pulse test : * $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation :

$$P = 0.330 \times I_{F(AV)} + 0.011 I_{F(RMS)}^2$$

Fig. 1: Average forward power dissipation versus average forward current (per diode).

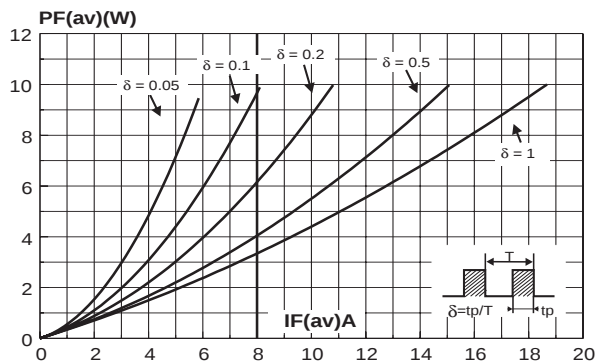


Fig. 2: Average current versus ambient temperature ($\delta=0.5$) (per diode).

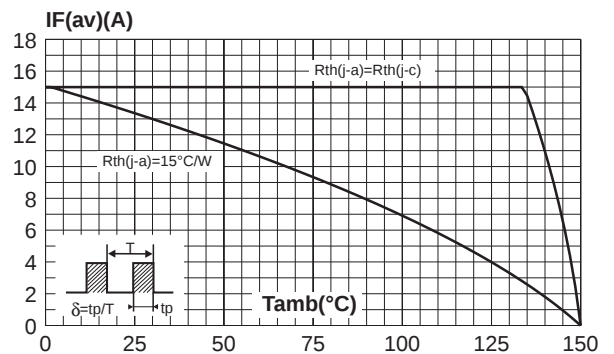


Fig. 3: Normalized avalanche power derating versus pulse duration.

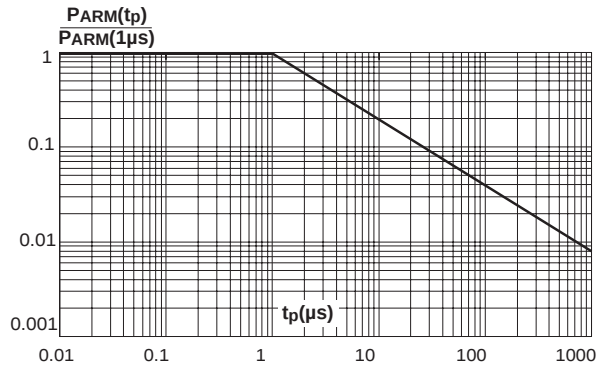


Fig. 4: Normalized avalanche power derating versus junction temperature.

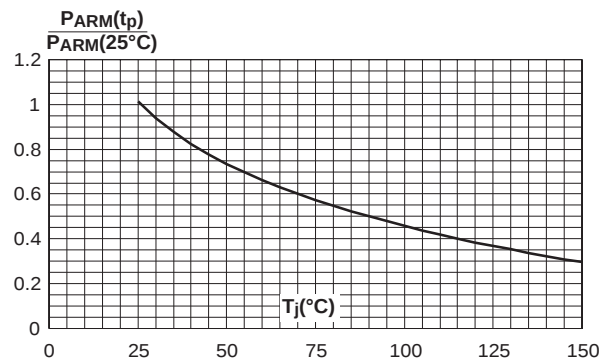


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values) (per diode).

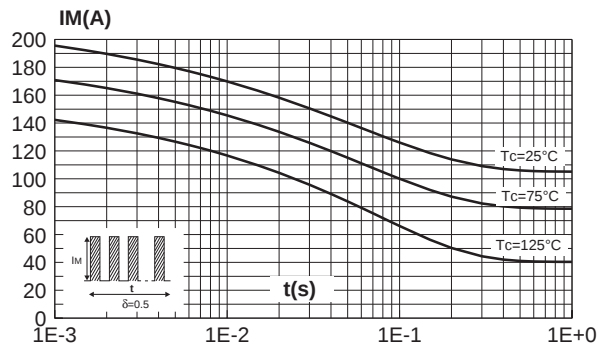


Fig. 6: Relative variation of thermal transient impedance junction to case versus pulse duration.

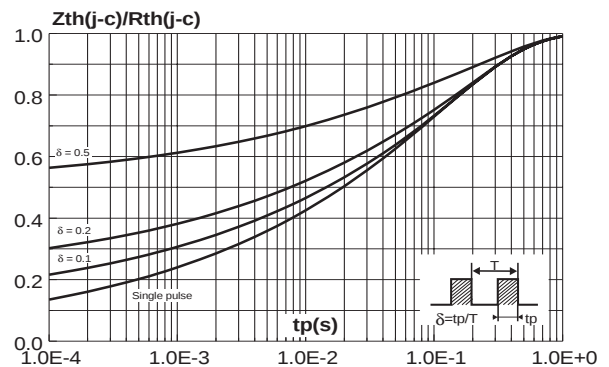


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values) (per diode).

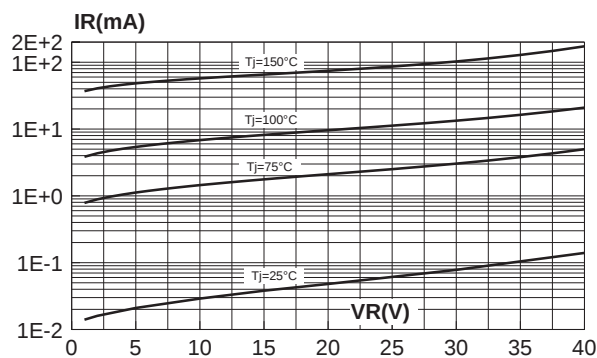


Fig. 8: Junction capacitance versus reverse voltage applied (typical values) (per diode).

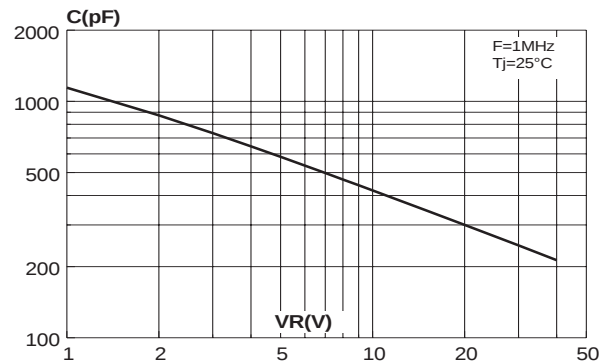


Fig. 9: Forward voltage drop versus forward current (maximum values) (per diode).

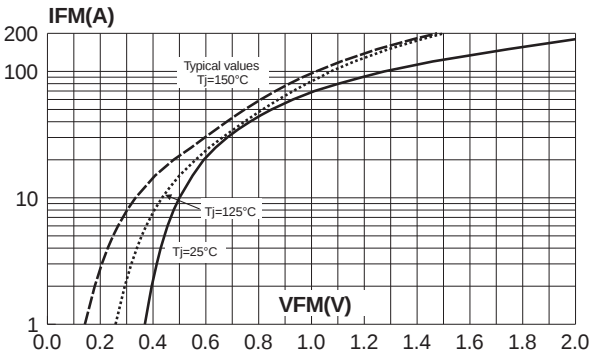
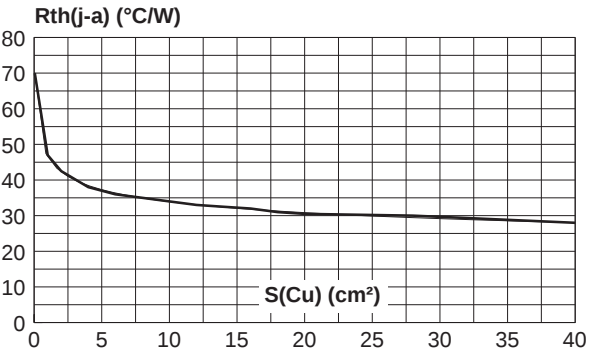
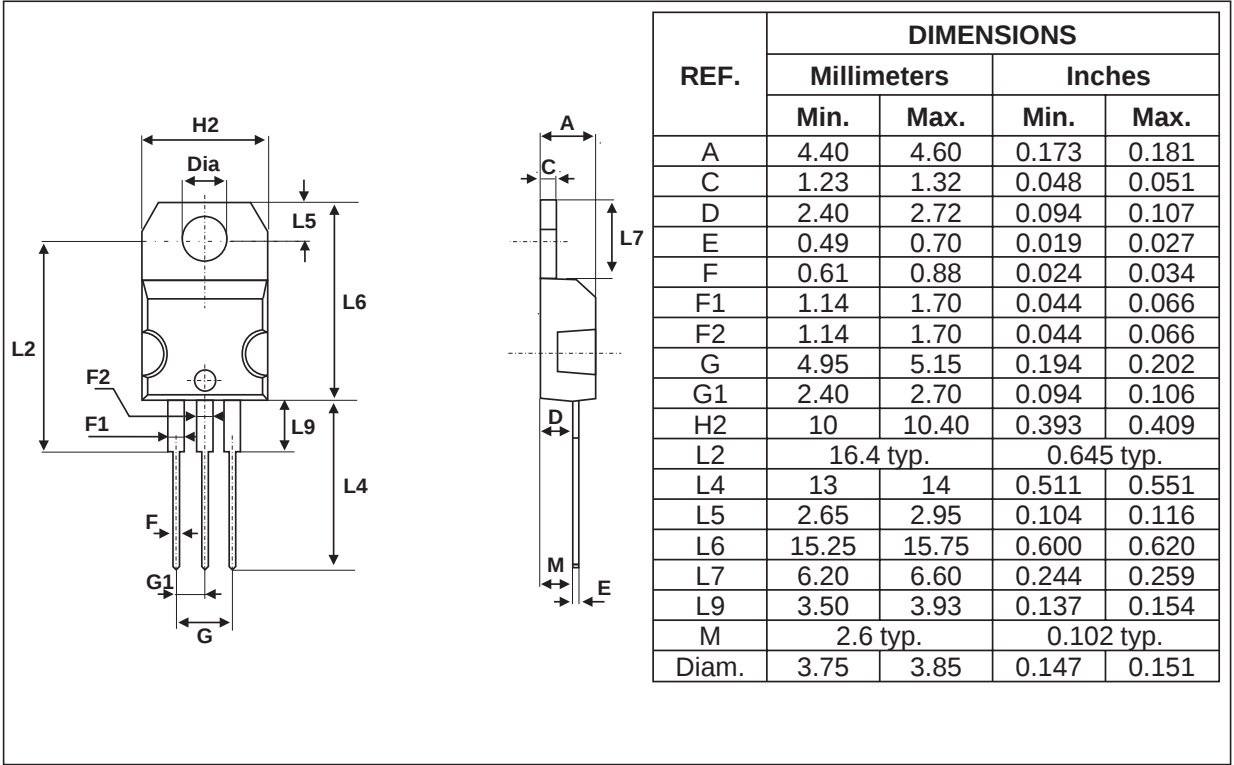


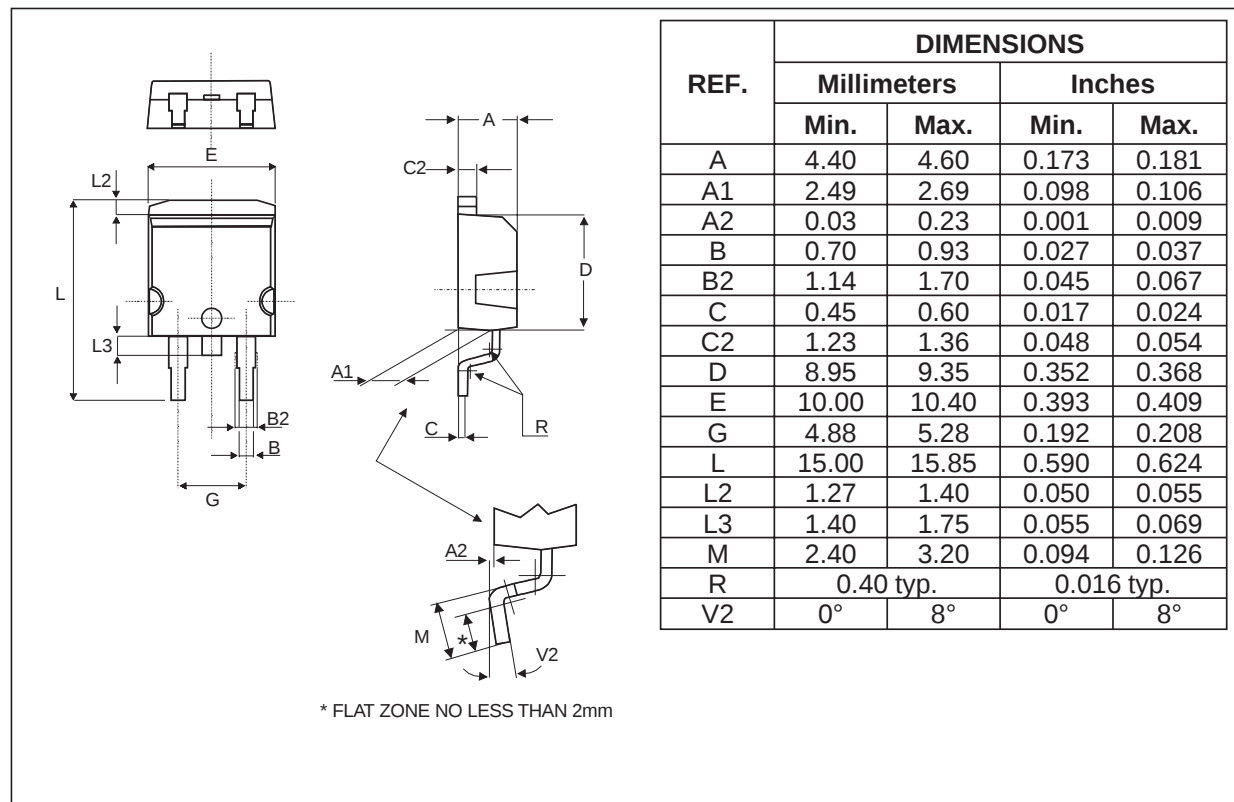
Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35μm) (STPS30L40CG only).



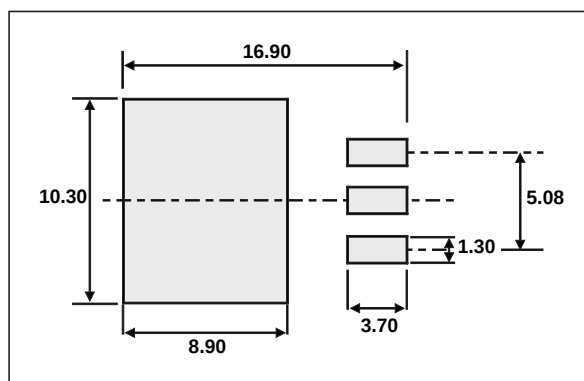
PACKAGE MECHANICAL DATA
TO-220AB



- COOLING METHOD : C
- RECOMMENDED TORQUE VALUE : 0.55 M.N
- MAXIMUM TORQUE VALUE : 0.70 M.N

PACKAGE MECHANICAL DATA
D²PAK


• COOLING METHOD : BY CONDUCTION
(METHOD C)

FOOT PRINT (in millimeters)
D²PAK


STPS30L40CG/CT/CW

PACKAGE MECHANICAL DATA TO-247

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F1		3.00		0.118		
F2		2.00		0.078		
F3	2.00		2.40	0.078		0.094
F4	3.00		3.40	0.118		0.133
G		10.90		0.429		
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50		0.728		
L3	14.20		14.80	0.559		0.582
L4		34.60		1.362		
L5		5.50		0.216		
M	2.00		3.00	0.078		0.118
V		5°		5°		
V2		60°		60°		
Dia.	3.55		3.65	0.139		0.143

- COOLING METHOD : C
- RECOMMENDED TORQUE VALUE : 0.8M.N
- MAXIMUM TORQUE VALUE : 1.0M.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS30L40CT	STPS30L40CT	TO-220AB	2g	50	Tube
STPS30L40CG	STPS30L40CG	D ² PAK	1.8g	50	Tube
STPS30L40CG-TR	STPS30L40CG	D ² PAK	1.8g	500	Tape & reel
STPS30L40CW	STPS30L40CW	TO-247	4.4g	30	Tube

- EPOXY MEETS UL94,V0

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